

LV8052GP, LV8052LP

Electrical Characteristics at $T_a = 25^\circ\text{C}$, $V_M = 5.0\text{V}$, $V_{CC} = 3.3\text{V}$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Input H-level voltage	V_{INH}	EN, MD1 to 3, IN1 to 2, INA to B, SWPI	2.5			V
Input L-level voltage	V_{INL}	EN, MD1 to 3, IN1 to 2, INA to B, SWPI			1.0	V
Input pin current	I_{INL}	$V_{IN} = 0\text{V}$			1.0	μA
	I_{INH}	$V_{IN} = 3.3\text{V}$	20	33	50	μA
Current drain at standby	I_{CCO}	EN, INA to B = "L"			1.0	μA
Current drain 1	I_M	EN = "H", MD1 to 3, IN1 to 2, INA to B = "H", no load	40	80	160	μA
Current drain 2	I_{CC}	EN = "H", MD1 to 3, IN1 to 2, INA to B = "H", no load	0.5	1.0	1.8	mA
V_{CC} low-voltage cut voltage	$V_{thV_{CC}}$		2.1	2.35	2.6	V
Low-voltage hysteresis voltage	V_{thHYS}		100	150	200	mV
Thermal shutdown temperature	TSD	Design guarantee	150	180	200	$^\circ\text{C}$
Thermal hysteresis width	ΔTSD	Design guarantee	20	40	60	$^\circ\text{C}$
Motor driver for SH (OUT1-2)						
Output ON resistance	Ronu	$I_O = 400\text{mA}$, upper ON resistance		0.65	0.80	Ω
	Rond	$I_O = 400\text{mA}$, lower ON resistance		0.45	0.60	Ω
Output leak current	I_{Oleak}				1.0	μA
Diode forward voltage	V_D	$I_D = -400\text{mA}$	0.7	0.9	1.2	V
Output constant current	I_{O1}	OUT2→OUT1, RRFS = 1 Ω , $3.0\text{V} \leq V_M \leq 5.0\text{V}$	117.5	125.0	132.5	mA
	I_{O2}	OUT1→OUT2, RRFS = 1 Ω , $3.0\text{V} \leq V_M \leq 5.0\text{V}$	117.5	125.0	132.5	mA
	I_{O3}	OUT2→OUT1, RRFS = 1 Ω , $2.9\text{V} \leq V_M \leq 3.1\text{V}$	116.9	123.0	129.1	mA
	I_{O4}	OUT1→OUT2, RRFS = 1 Ω , $2.9\text{V} \leq V_M \leq 3.1\text{V}$	116.9	123.0	129.1	mA
Stepping motor driver for AF (OUT2-3, OUT6-7)						
Output ON resistance	Ronu	$I_O = 400\text{mA}$, upper ON resistance		0.65	0.80	Ω
	Rond	$I_O = 400\text{mA}$, lower ON resistance		0.45	0.60	Ω
Output leak current	I_{Oleak}				1.0	μA
Diode forward voltage	V_D	$I_D = -400\text{mA}$	0.7	0.9	1.2	V
Motor driver for ZOOM (OUT4-8)						
Output ON resistance	Ronu	$I_O = 400\text{mA}$, upper ON resistance		0.65	0.80	Ω
	Rond	$I_O = 400\text{mA}$, lower ON resistance		0.45	0.60	Ω
Output leak current	I_{Oleak}				1.0	μA
Diode forward voltage	V_D	$I_D = -400\text{mA}$	0.7	0.9	1.2	V
Motor driver for AE (OUT5-6)						
Output ON resistance	Ronu	$I_O = 400\text{mA}$, upper ON resistance		0.65	0.80	Ω
	Rond	$I_O = 400\text{mA}$, lower ON resistance		0.45	0.60	Ω
Output leak current	I_{Oleak}				1.0	μA
Diode forward voltage	V_D	$I_D = -400\text{mA}$	0.7	0.9	1.2	V
Photo sensor driving transistor (PI)						
Output ON resistance	Ron	$I_O = 30\text{mA}$		3.0	6.0	Ω
Output leak current	I_{Oleak}				1.0	μA

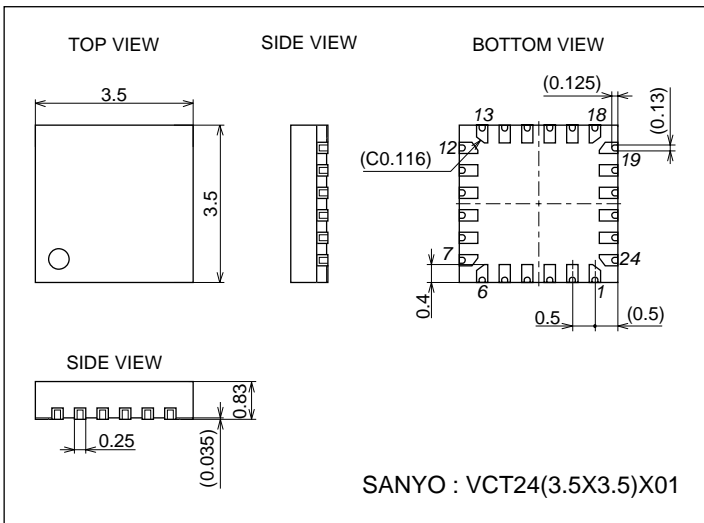
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Package Dimensions

unit : mm (typ)

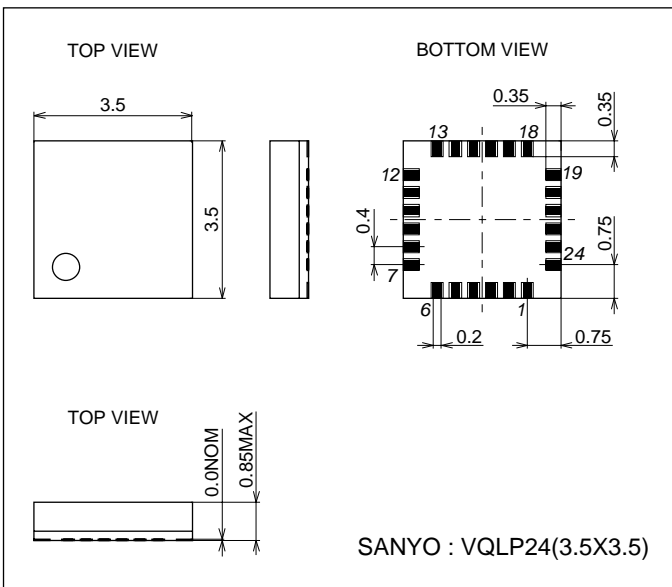
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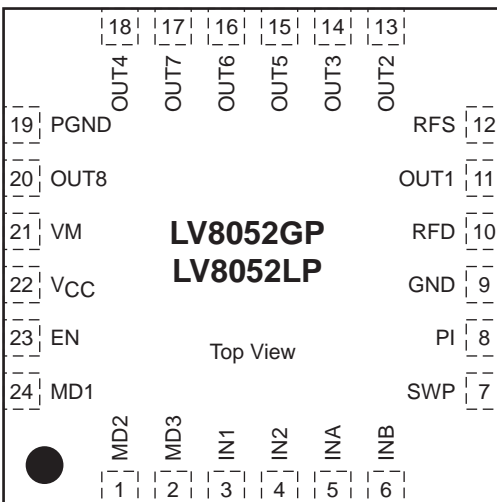
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[LV8052LP]



Pin Assignment

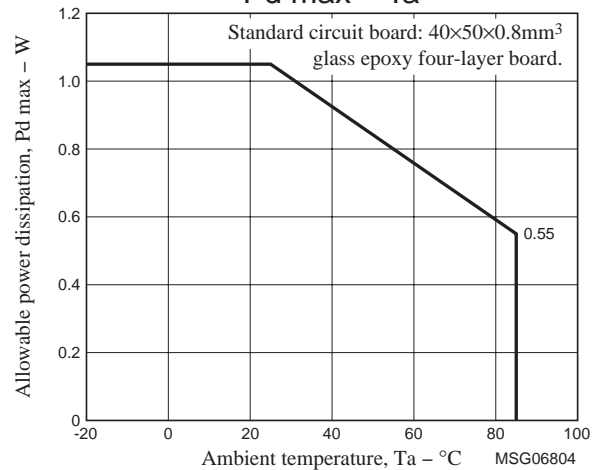
* The pin assignment is the same as LV8052GP and LV8052LP.



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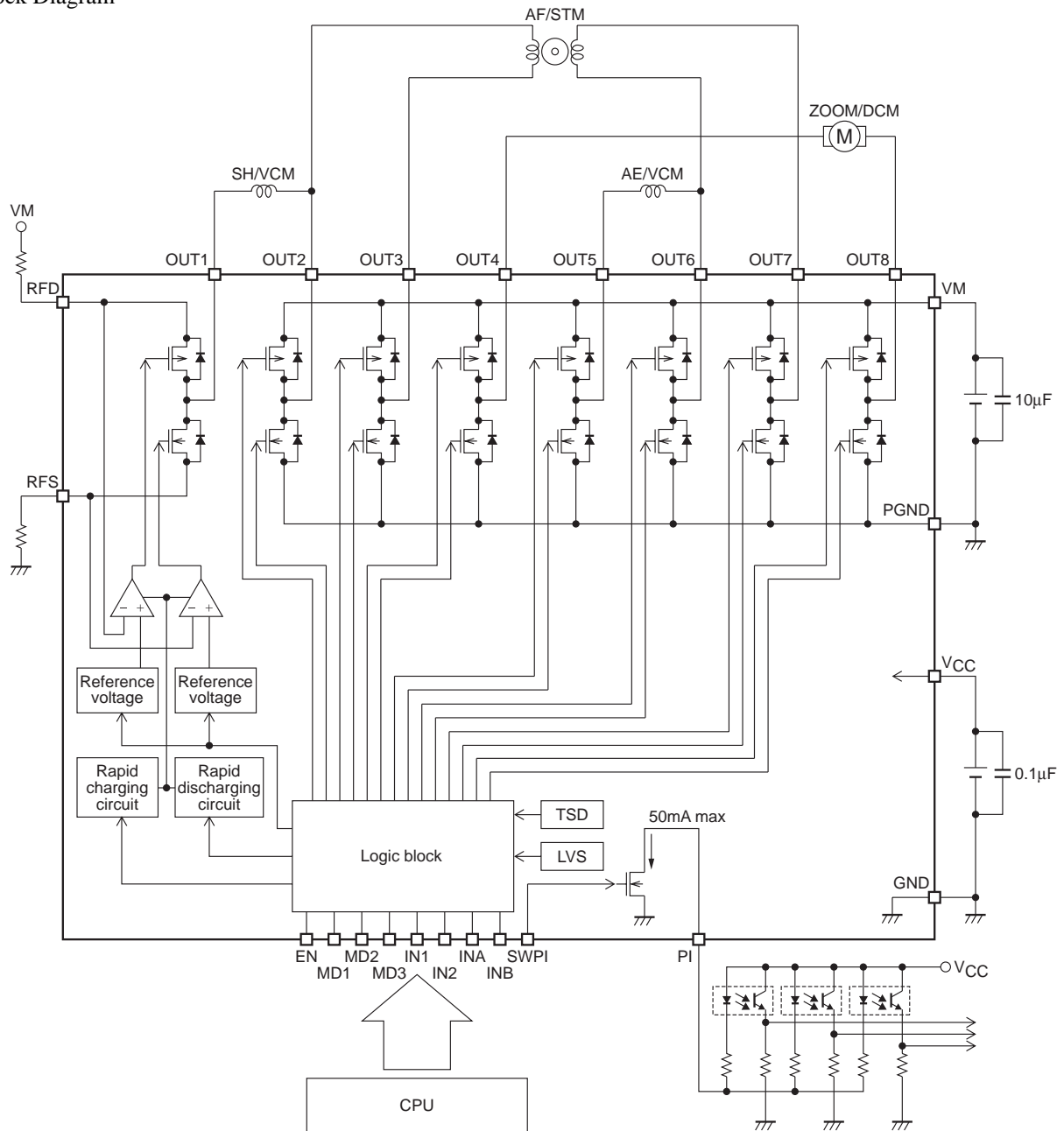
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Pd max - Ta



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Block Diagram



Pin Function

Pin No.	Pin name	Function	Equivalent circuit
1 2 3 4 5 6	MD2 MD3 IN1 IN2 INA INB	Control signal input pin	
7	SWPI	Control signal input pin (photo sensor driving transistor)	
23 24	EN MD1	Control signal input pin	
10	RFD	OUT1→OUT2 Current detection resistance connection pin	
11	OUT1	Output pin	
12	RFS	OUT1→OUT2 Current detection resistance connection pin	
13 14 15 16 17 18 20	OUT2 OUT3 OUT5 OUT6 OUT7 OUT4 OUT8	Output pin	

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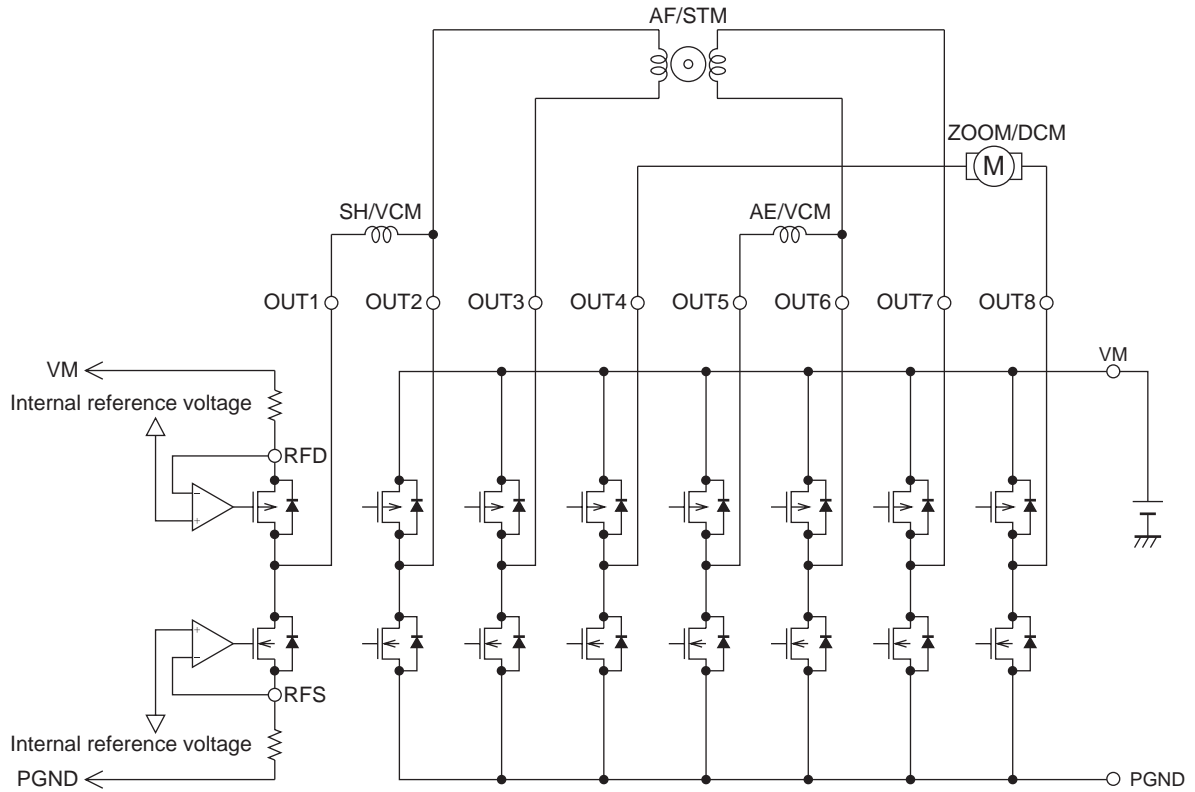
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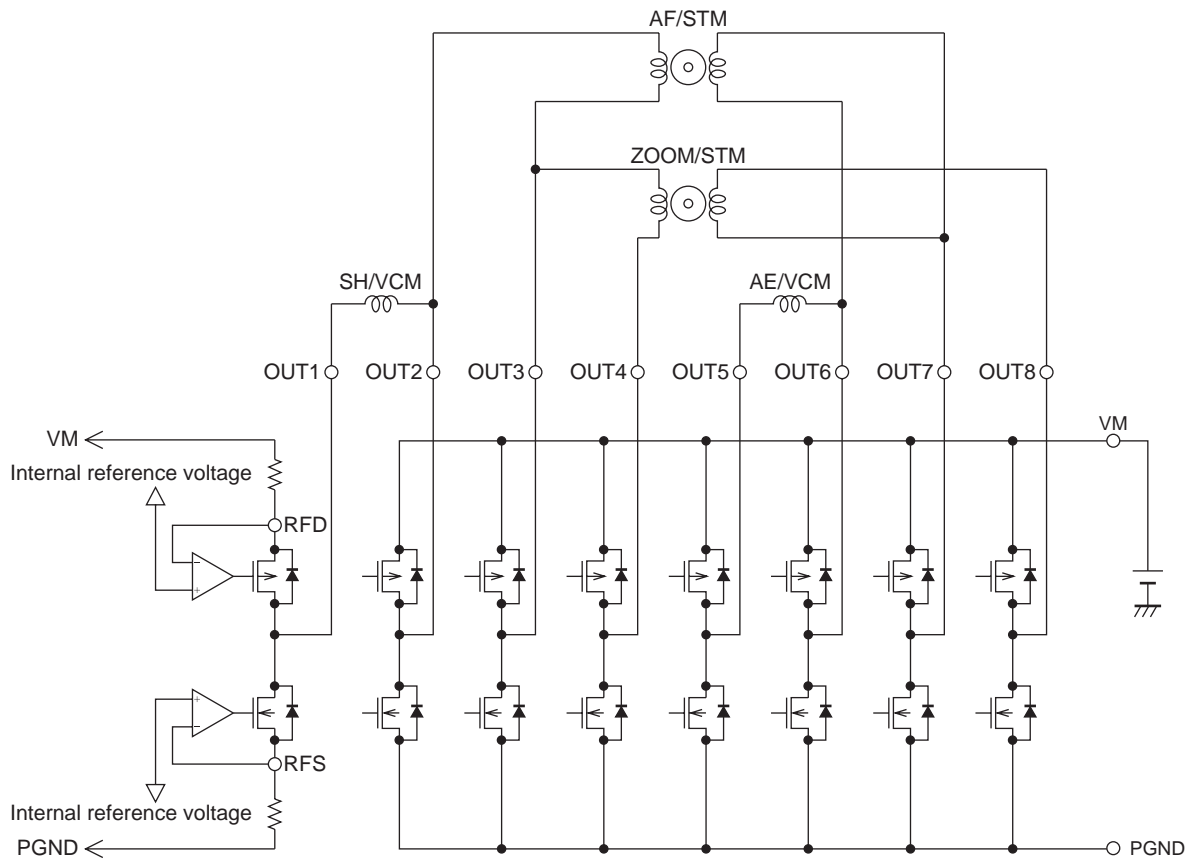
Pin No.	Pin name	Function	Equivalent circuit
8	PI	Photo sensor driving transistor output pin	
10	RFD	OUT1→OUT2 Current detection resistance connection pin	
12	RFS	OUT1→OUT2 Current detection resistance connection pin	
9	GND	Signal GND	
19	PGND	Power GND	
21	VM	Motor power connection pin	
22	VCC	Logic power connection pin	

Sample Application Circuit

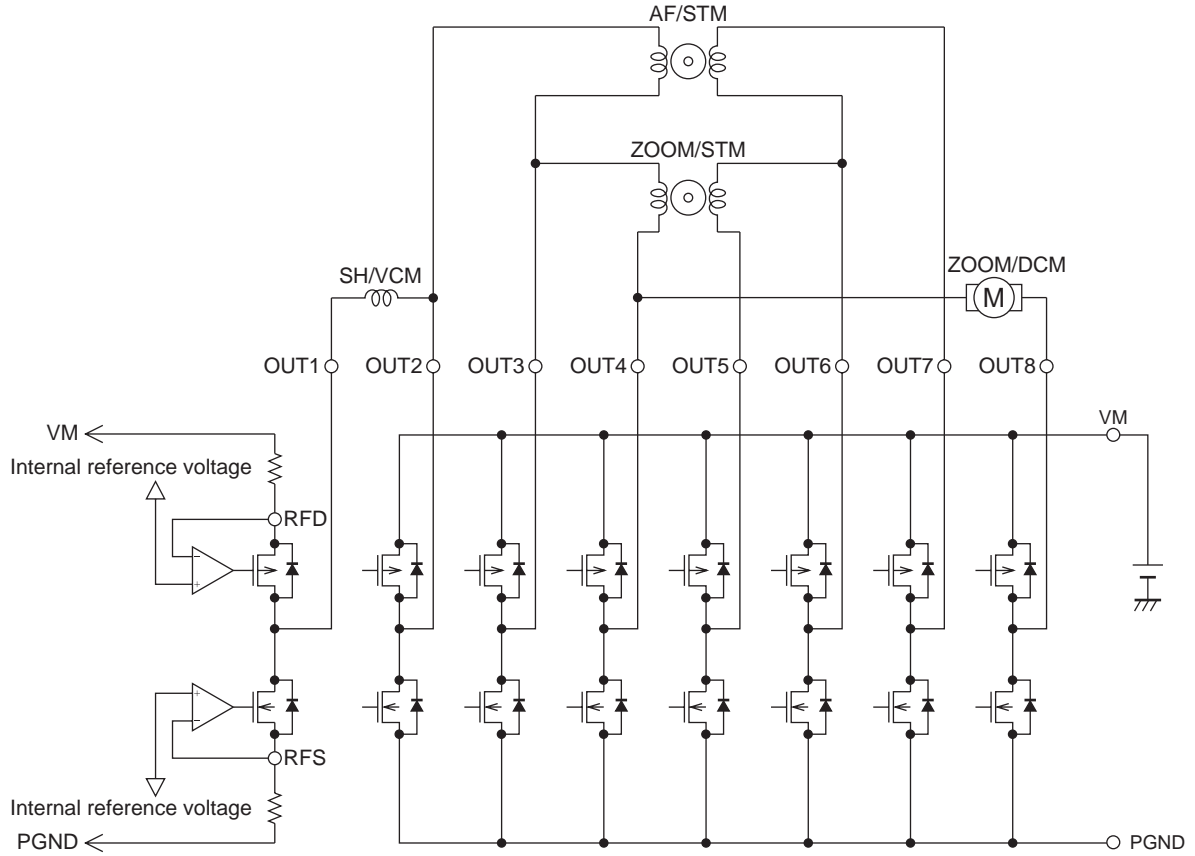
[Example 1]



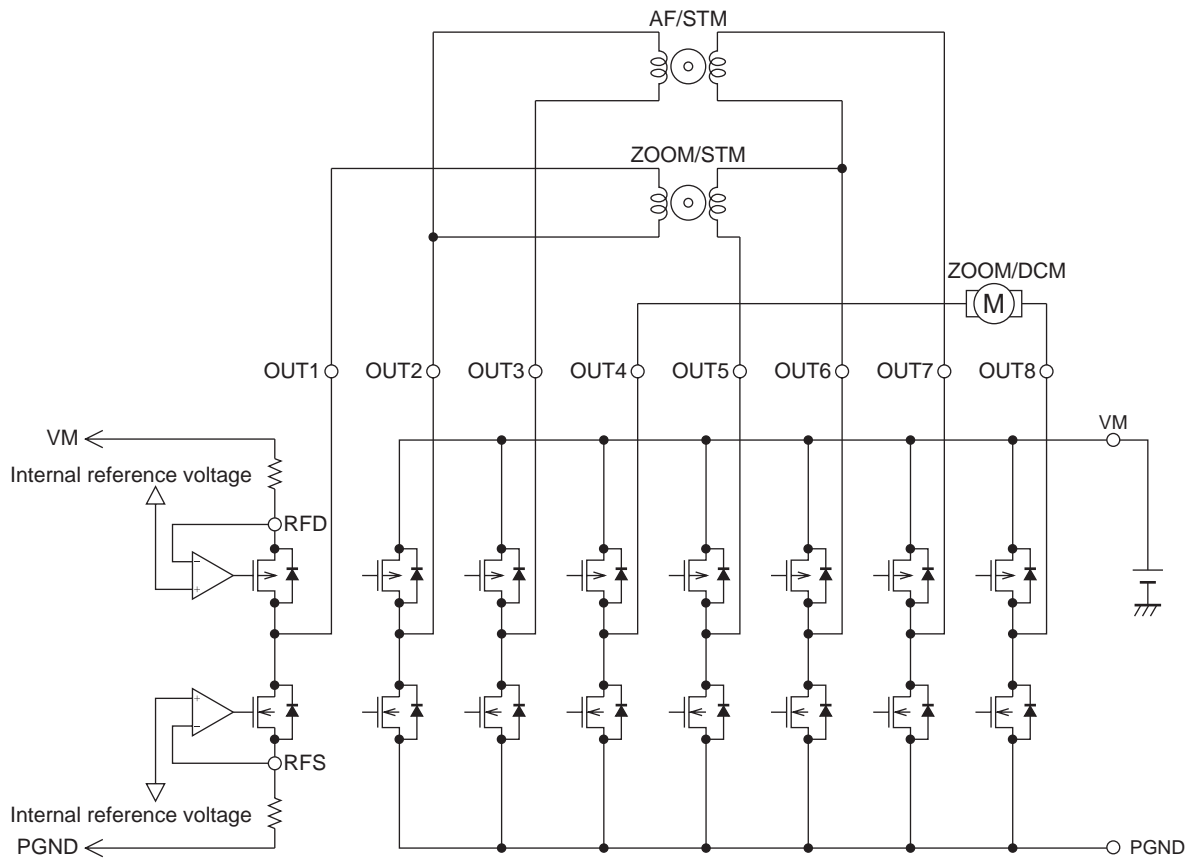
[Example 2]



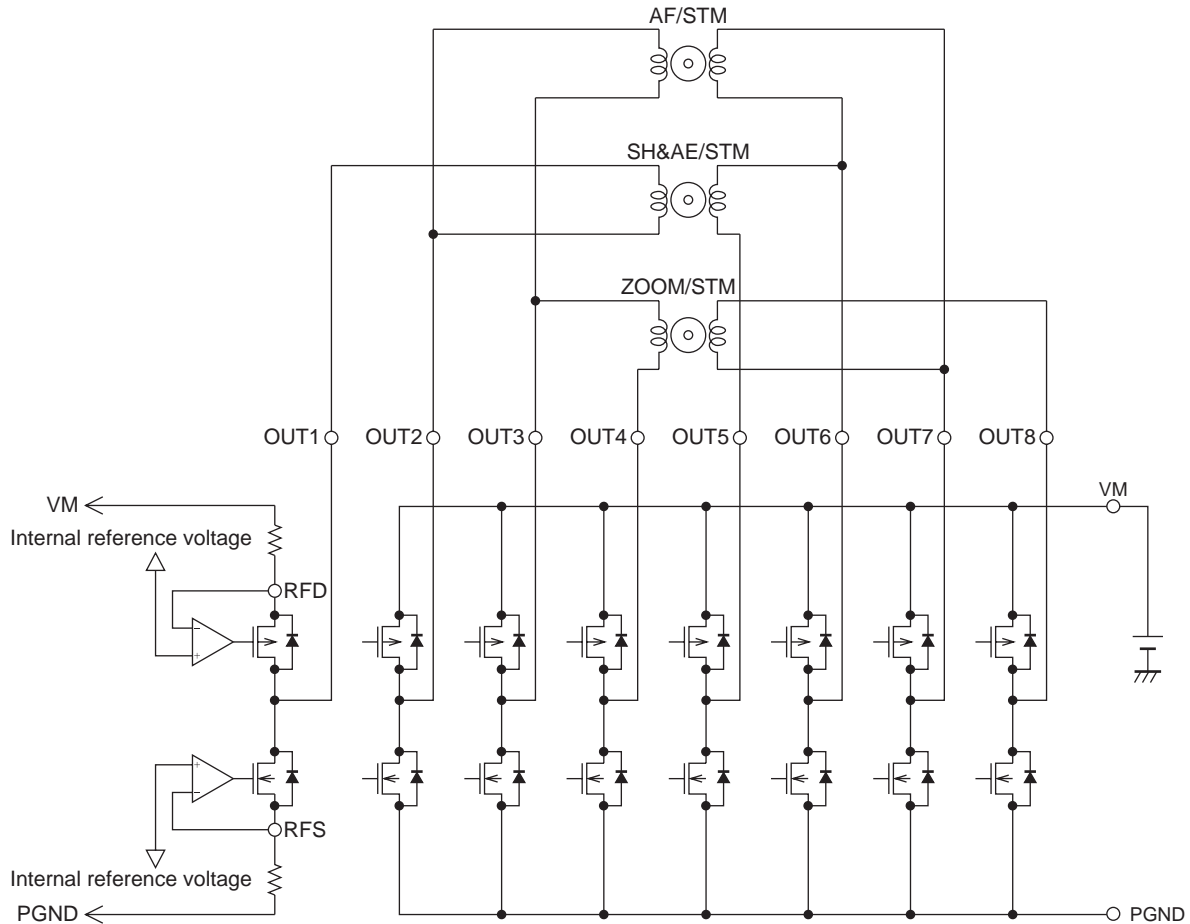
[Example 3]



[Example 4]



[Example 5]



Design Considerations

1. Method to calculate the set current value for shutter control

The output current can be set from the internal reference voltage and the detection resistors, each connected between VM and RFD pins and between RFS pin and GND.

$$I_{OUT} = \text{Internal reference voltage } 0.125\text{V} \div \text{detection resistor}$$

From the above equation, the current value to flow from OUT2 to OUT1 when the detection resistor 1Ω is connected between the RFS pin and GND can be determined to be about 125mA.

Similarly, the current value to flow from OUT1 to OUT2 when the detection resistor 1Ω is connected between VM and RFD can be determined to be about 125mA.

2. Changeover between the constant current and saturation drive

Saturation drive is made by deleting the detection resistors between VM and RFD pins and between the RFS pin and GND.

3. OUT4 and OUT8 independent control with INA and INB pins

When the INA or INB pin is set at “H”, OUT4 and OUT8 are activated regardless of the input conditions of MD1 to MD3 and IN1 to IN2.

4. Photo sensor driving transistor

By setting the SWPI pin to “H”, the photo sensor driving transistor is activated.

When thermal shutdown and V_{CC} low-voltage cut circuits are activated, OUT1 through OUT8 are turned OFF under control of the internal circuit. But the output (PI) of photo sensor driving transistor continues operation.

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